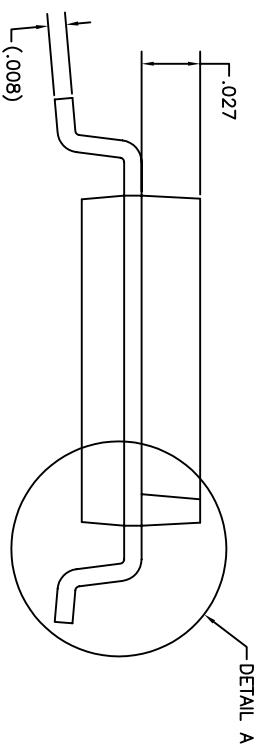
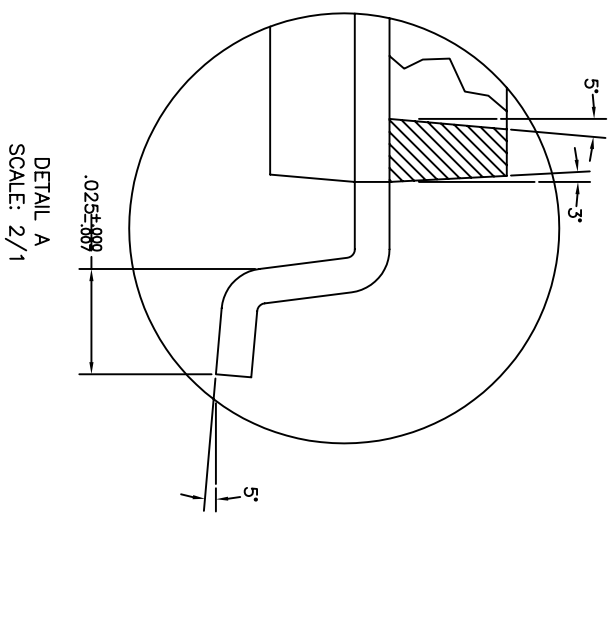
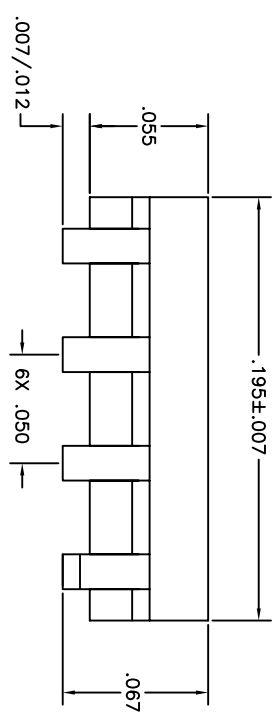
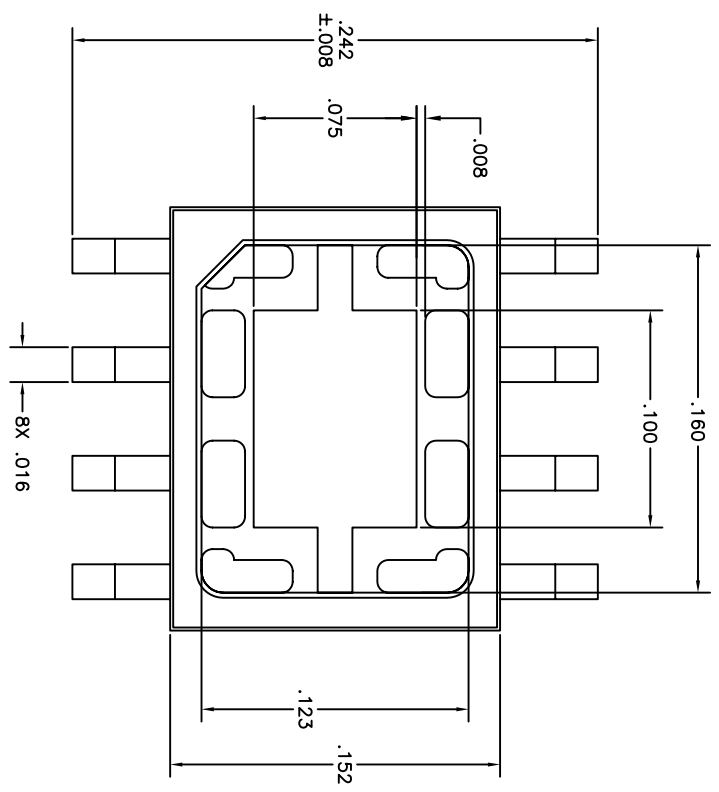


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REVISIONS			APPROVED
EON NO.	DATE	DESCRIPTION	D.BENAVANDO
10505	10/31/05	PRODUCTION RELEASE	



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEADFRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL Au PLATE.
 4. FRAME THICKNESS: .0080±.0003.
 5. JEDEC OUTLINE: MS-012.



THIRD ANGLE
PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE: X.XXX ±.001 X.XXXX ±.0005
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN	W. GRIFFITTS	DATE	10/28/05
APP BY	P. FLASKERUD	DATE	10/28/05
CUSTOMER	---		

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SIZE	PART NO.	REV
A	SOIC150-08-0P-01	2
SCALE	NONE	
CAD FILE	SOIC150-08-0P-01-R2.DWG	
SHEET	1 OF 1	

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